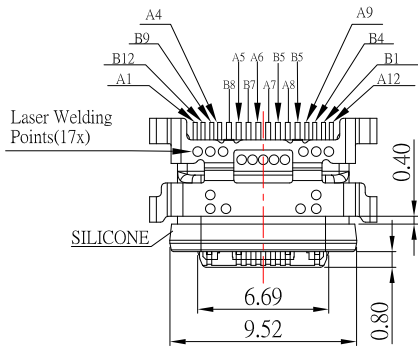


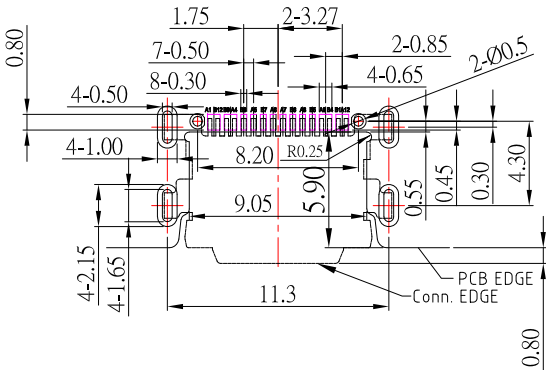
IPX8



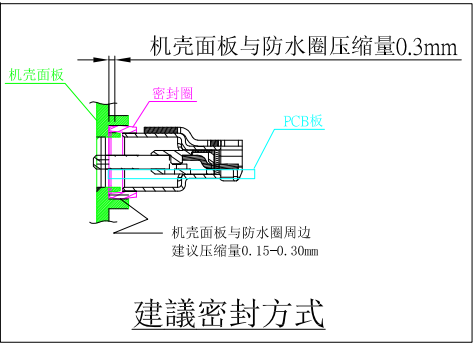
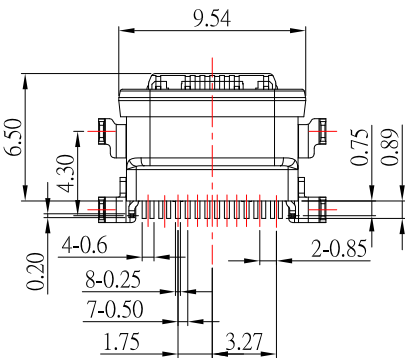
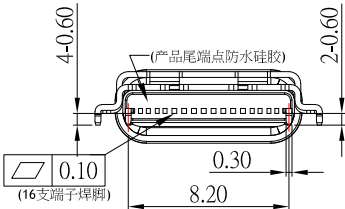
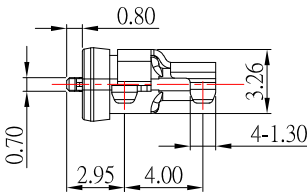
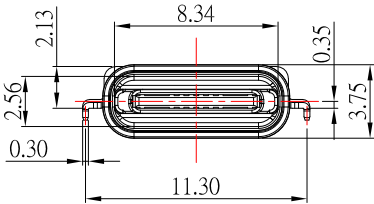
SBC-WP160M4-20x-S175

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT



SPECIFICATIONS

Electrical:

- 1.Rating: 5.0V , 3.0 A
- 2.Contact Resistance: 40 mΩ Max
- 3.Insulation Resistance: 100 MΩ Min

Mechanical:

- 1.Connector Mate and Unmate Force
 - 1.1 Mate force: 5~20 N
 - 1.2 Unmate force: 8~20 N

Material:

- 1.Housing: PA9T
- 2.Contact: C18400
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

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TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	11/19/25	FINISH	MODLE	USB TYPE C 2.0 沉板 2.13mm 防水型IPX8
CHECKED BY:	DATE	SCALE	DWG NO.	SBC-WP160M4-20x-S175
Jacky Chen	11/19/25	1 : 1	PART NO.	SBC-WP160M4-20x-S175
APPROVED BY:	DATE	SHEET NO.	1 of 1	VER
Tony Kao	11/19/25			R1